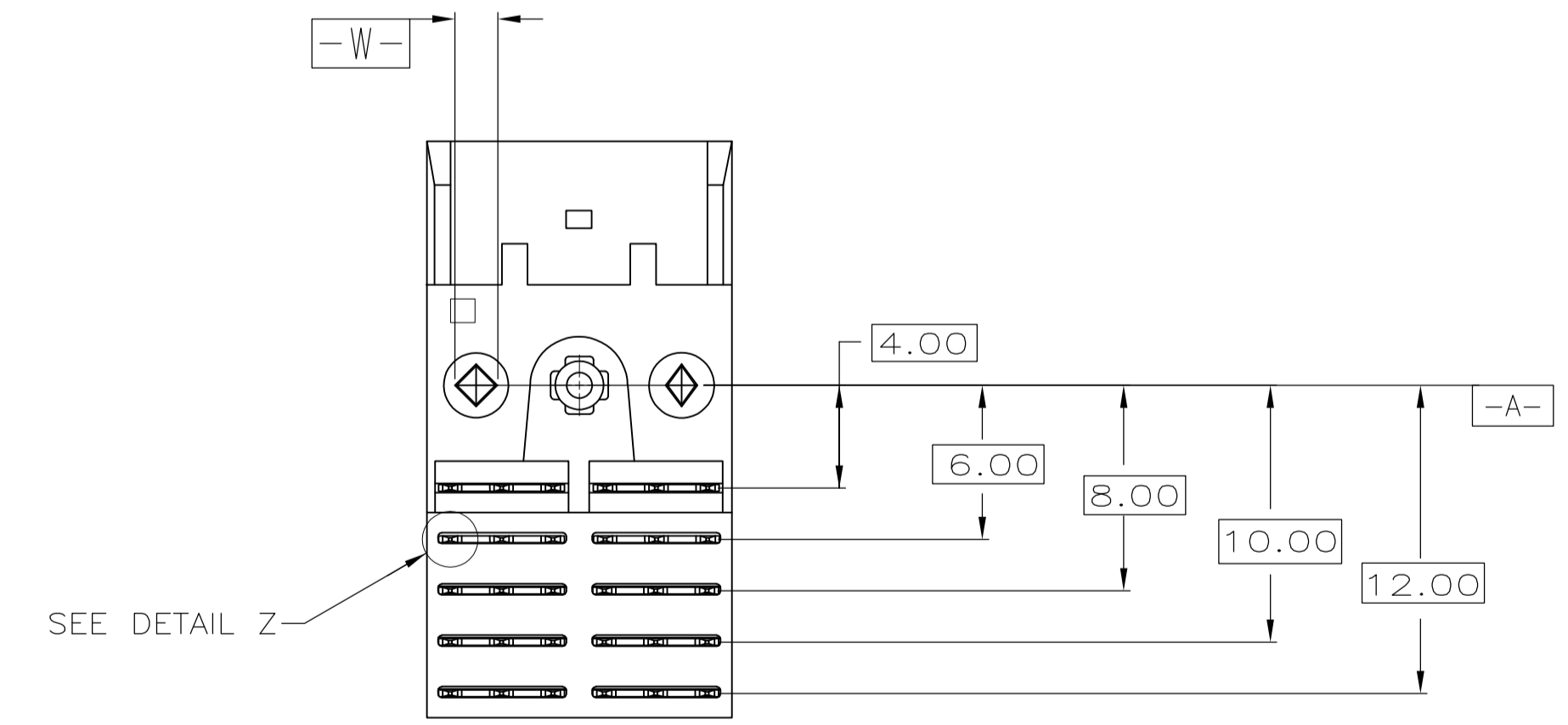
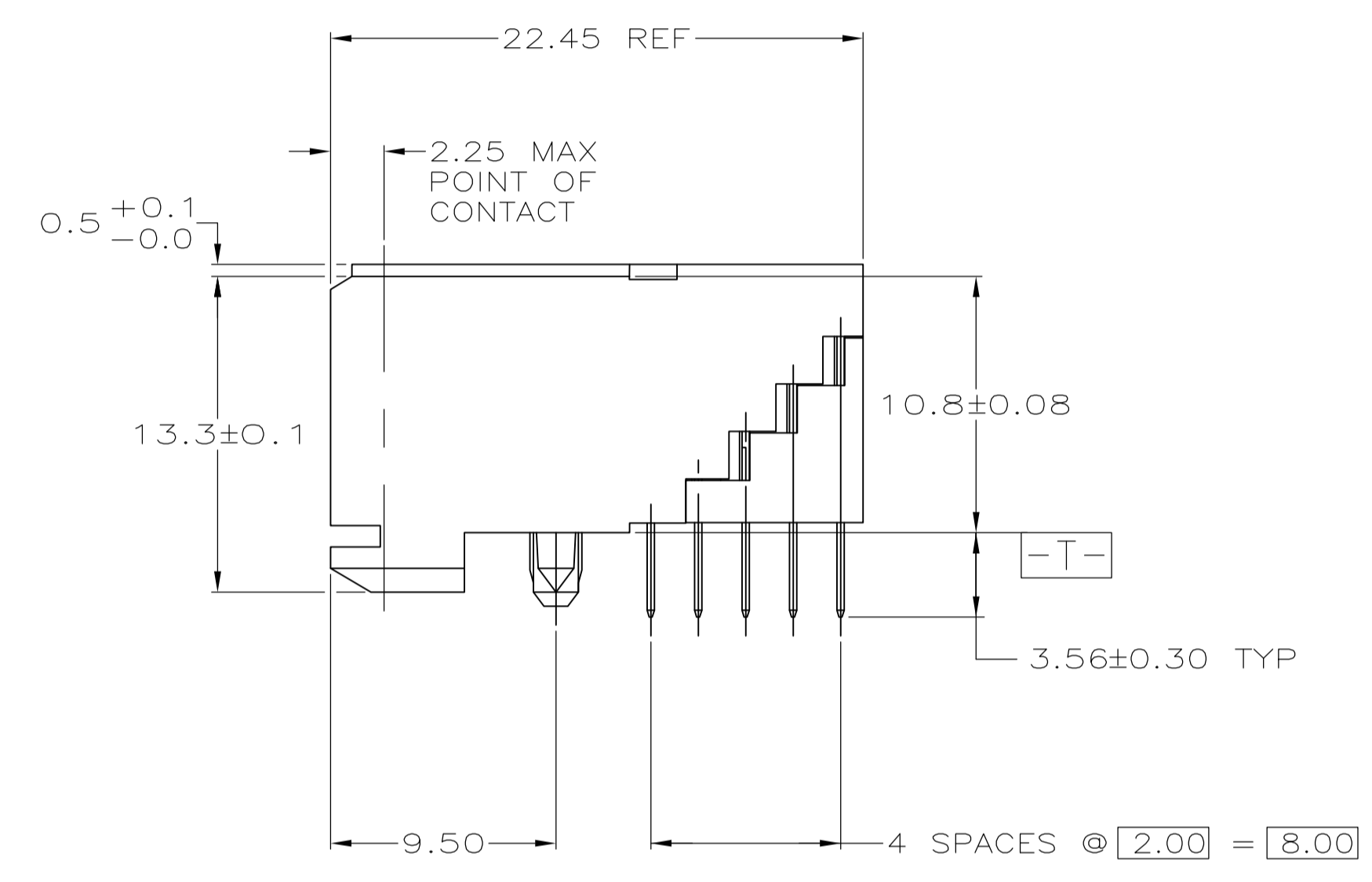
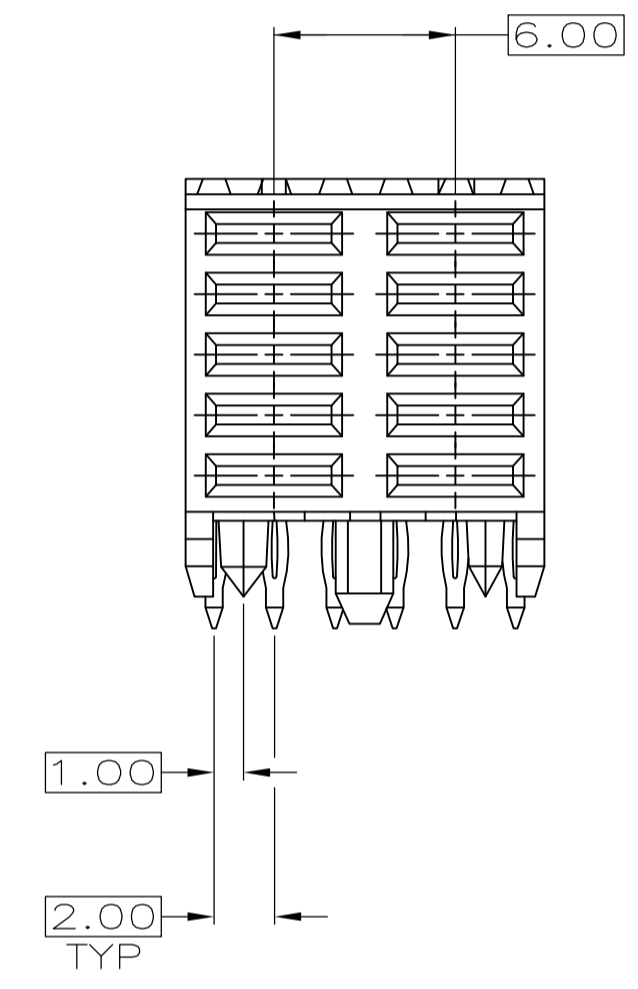
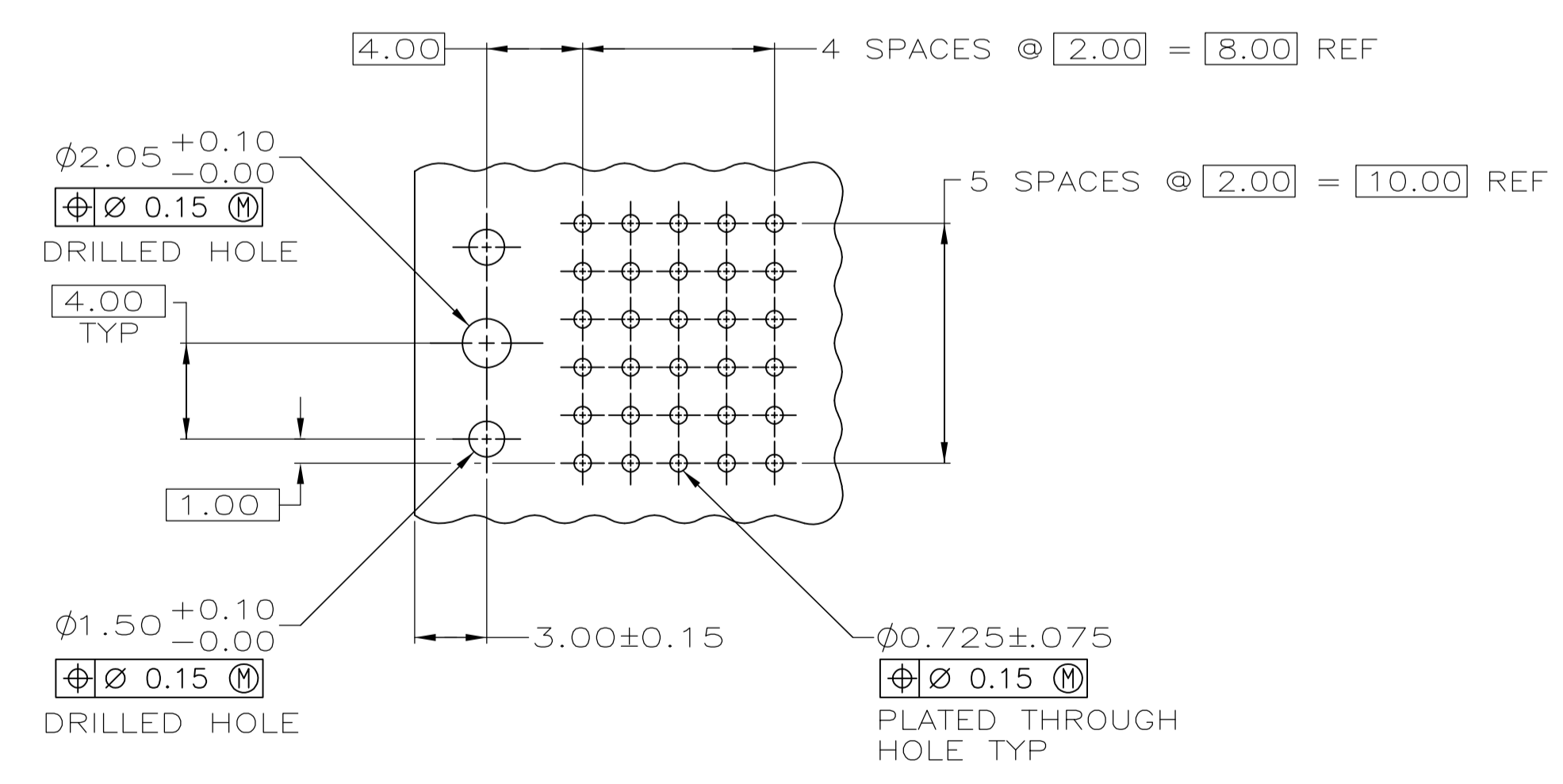


DETAIL Z  
SCALE 20:1

- ① HOUSINGS MATERIAL: LIQUID CRYSTAL POLYMER.
- ② CONTACT MATERIAL: COPPER ALLOY
- ③ CONTACT FINISH:  
 UNDERPLATE (ENTIRE CONTACT):  
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290  
 ON MATING SURFACES:  
 FLASH GOLD PER ASTM B 488, OVER  
 0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR  
 0.00076 MIN GOLD PER ASTM B 488 OVER UNDERPLATE.  
 ON LEADS:  
 0.00127 MIN TIN-LEAD OVER UNDERPLATE.  
 LUBRICATION (MIN MATING SURFACES):  
 SURFACE CONDITIONER AFTER PLATING.



SEE DETAIL Z



RECOMMENDED CURCUIT PATTERN  
PER IPC-D300 TYPE II, CLASS C  
(COMPONENT SIDE)

③	536676-1
FINISH	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN T. SHUEY 5-29-98		Tyco Electronics Corporation	
DIMENSIONS: mm		CHK D. KOVALICK 6-22-98		Harrisburg, PA 17105-3608	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD D. KOVALICK 6-22-98		NAME R/OPT ASSEMBLY POWER Z+ BACK 2mm FB	
0 PLC ± -		PRODUCT SPEC		R/A,5 ROW,10 POSN,W/TAIL ORGANIZER	
1 PLC ± -		APPLICATION SPEC		RESTRICTED TO	
2 PLC ± 0.13		WEIGHT		A1 00779 C=536676	
3 PLC ± -		CUSTOMER DRAWING		SCALE: 4:1 SHEET: 1 OF 1 REV: J1	
4 PLC ± -					
ANGLES ± -					